



SOT612-3

plastic thermal enhanced low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm; exposed die pad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP144
Package type industry code	HLQFP144
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	5-7-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	19.9	-	20	20.1	mm
A	seated height	1.4	-	1.5	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	144	-	

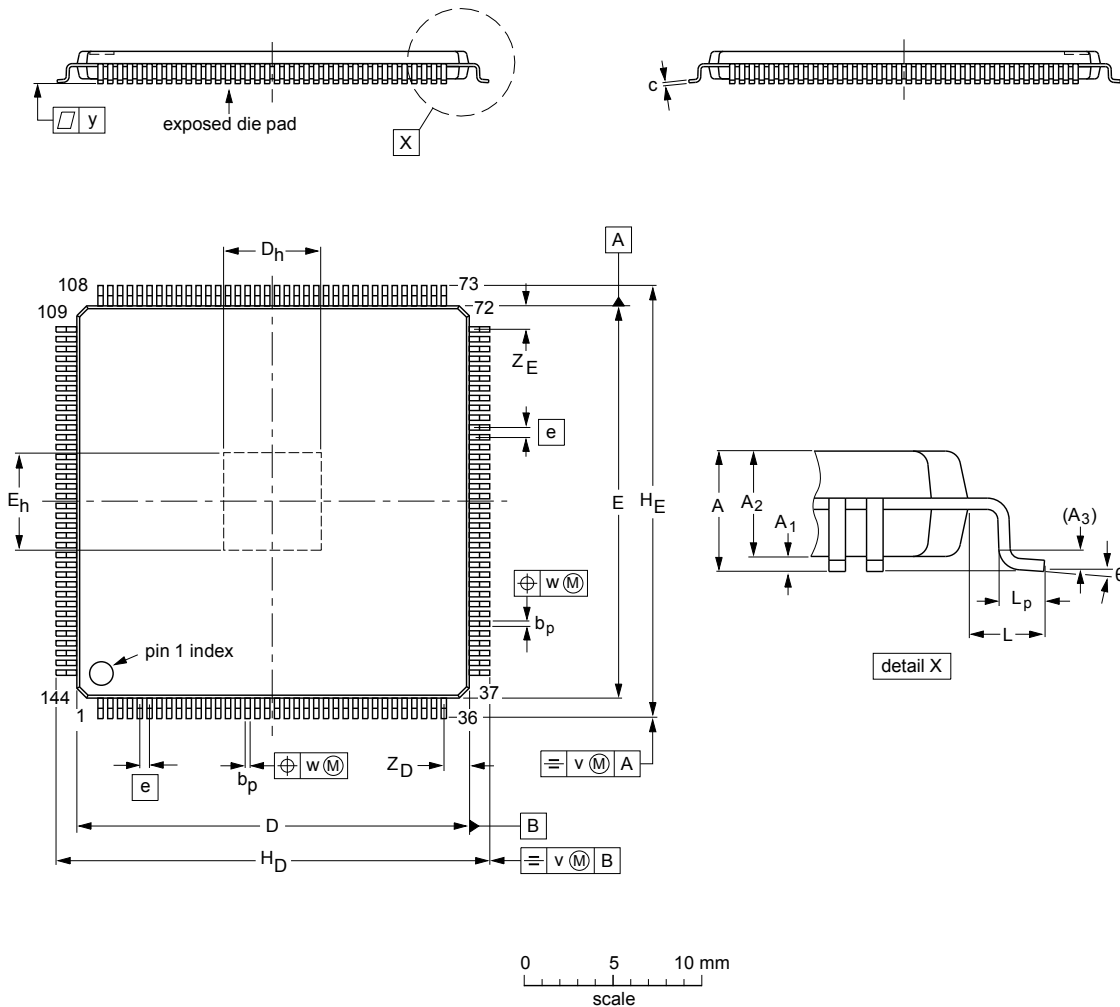


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2. Package outline

HLQFP144: plastic thermal enhanced low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.6	0.12 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	20.1 19.9	5.7 5.5	20.1 19.9	5.7 5.5	0.5	22.15 21.85	22.15 21.85	1	0.75 0.45	0.2	0.08	0.08	1.4 1.1	1.4 1.1	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT612-3		MS-026				-02-07-12 04-07-05

Fig. 1. Package outline HLQFP144 (SOT612-3)

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3. Soldering

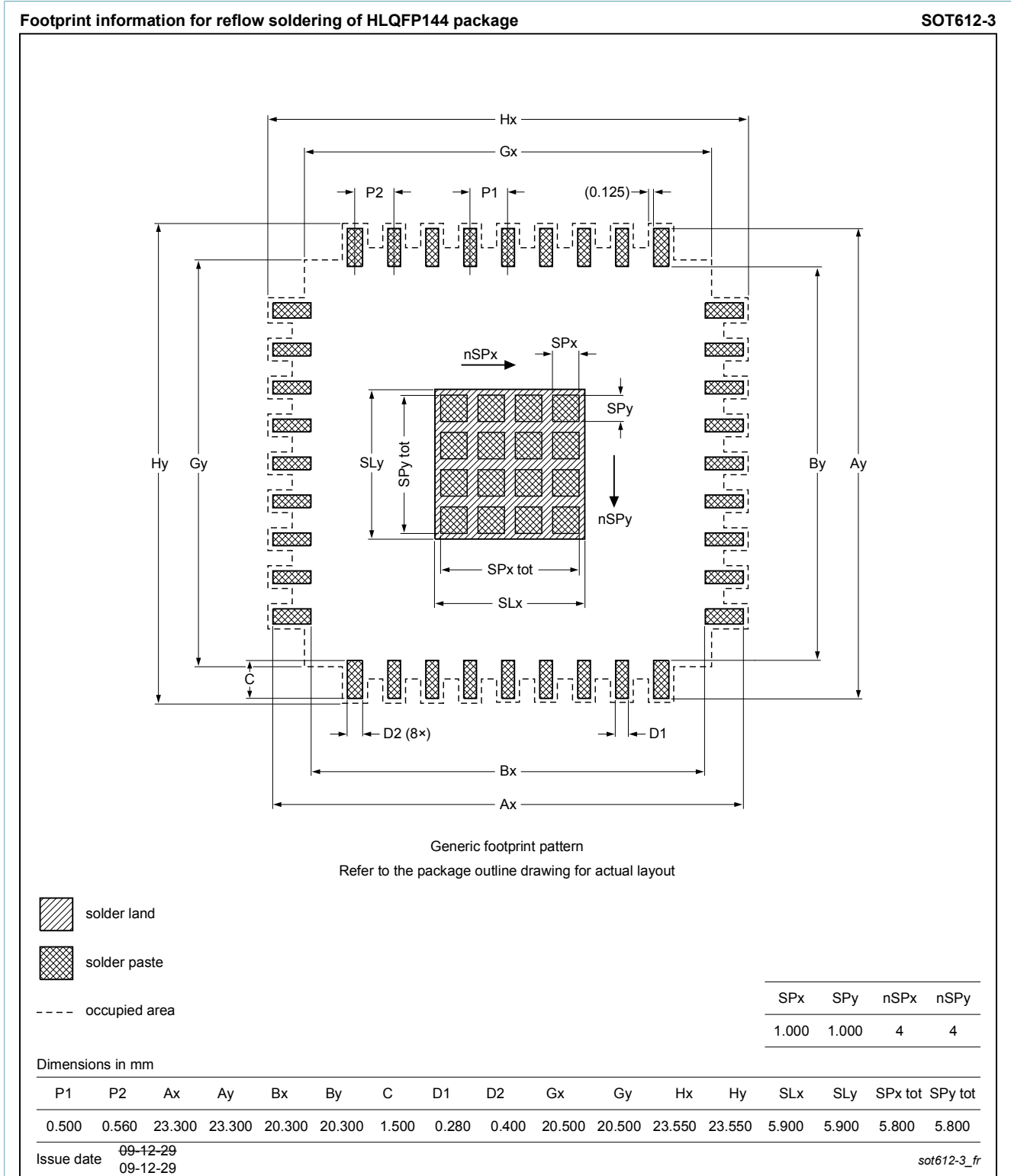


Fig. 2. Reflow soldering footprint for HLQFP144 (SOT612-3)

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4. Legal information

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For more information, please visit: <http://www.nxp.com>
For sales office addresses, please send an email to: salesaddresses@nxp.com
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